IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Previously Presented): A multi-layer printed wiring board comprising:

a core substrate having a plurality of through holes therein, the through holes in the core substrate being disposed so that a ground through hole and a power through hole adjoin each other, wherein a distance between the ground through hole and the power through hole is in a range of 60 to 550 $\mu$m;

an interlayer insulating layer formed on the core substrate;

a conductive layer formed on the interlayer insulating layer; and

a plurality of via holes provided in the insulating layer and configured to provide electrical connection between the conductive layer and through holes.

Claim 2 (Previously Presented): The multi-layer printed wiring board according to claim 1, wherein the ground through hole in the core substrate including two or more ground through holes and the power through hole including two or more power through holes, such that the ground through holes and the power through holes are disposed in a grid formation or in a staggered formation at adjacent positions.

Claim 3 (Canceled).

Claim 4 (Previously Presented): The multi-layer printed wiring board according to claim 1, wherein the diameter of the ground through hole is 50 to 500 $\mu$m and the diameter of the power through hole is 50 to 500 $\mu$m.

Claim 5 (Previously Presented): The multi-layer printed wiring board according to claim 1, wherein at least one through hole of the ground through holes and the power through holes comprises two or more through holes -in a stack structure through all -layers of the multi-layer printed wiring board up to an outermost layer.

Claim 6 (Original): The multi-layer printed wiring board according to any one of claims 1, 2 or 5 wherein the ground through hole and the power through hole are disposed just below an IC chip.

Claim 7 (Original): The multi-layer printed wiring board according to claim 1 or 2 wherein the thickness of conductive layer on the core substrate is larger than the thickness of the conductive layer on the interlayer insulating layer.

Claim 8 (Original): The multi-layer printed wiring board according to claim 1 or 2 wherein assuming that the thickness of the conductive layer on the core substrate is $\alpha$ 1 and the thickness of the conductive layer on the interlayer insulating layer is $\alpha 2$, $\alpha 2 < \alpha 1 \leqq 40\alpha 2$.

Claim 9 (Original): The multi-layer printed wiring board according to claim 8 wherein the $\alpha 1$ is in a relation of $1.2\alpha 2 \leqq \alpha 1 \leqq 40\alpha 2$.

Claim 10 (Previously Presented): The multi-layer printed wiring board according to claim 7, wherein each conductive layer of the core substrate is conductive layer for power layer or conductive layer for grounding.

Claim 11 (Previously Presented): The multi-layer printed wiring board according to claim 1, wherein a capacitor is mounted on the surface thereof.

Claim 12 (Currently Amended): The multi-layer printed wiring board according to claim 1 or 2 wherein the core substrate is a multi-layer core substrate composed of three or more layers and including a thick conductive layer as an inner layer, and a conductive layer as a surface layer, and

the conductive layer of each inner layer of the core substrate and the conductive layer of each surface layer are a conductive layer for power layer or a conductive layer for grounding.

Claim 13 (Original): The multi-layer printed wiring board according to claim 1 or 2 wherein the core substrate is a multi-layer core substrate composed of three layers and including a thick conductive layer as an inner layer, and

the conductive layer of each inner layer of the core substrate is conductive layer for power layer or conductive layer for grounding and the conductive layer on the front surface side is composed of signal line.

Claim 14 (Previously Presented): The multi-layer printed wiring board according to claim 12, wherein the thickness of the conductive layer of the inner layer of the core substrate is larger than the thickness of the conductive layer on the interlayer insulating layer.

Claim 15 (Original): The multi-layer printed wiring board according to claim 12 or 13 wherein the conductive layer in the inner layer of the core substrate is composed of two or more layers.

Claim 16 (Currently Amended): The multi-layer printed wiring board according to claim 12, wherein:

the core substrate is so constructed that the thick conductive layer ~~of the~~ as an inner layer comprises first and second thick conductive layers ~~is~~ formed on ~~each of both~~ respective sides of a metallic plate which is electrically ~~insulating, through~~ insulated by a resin layer, and ~~further,~~ the conductive layer ~~on the~~ as a surface ~~side~~ layer is formed outside the conductive layer ~~of the~~ as an inner layer ~~through~~ interposed by a resin layer.

Claim 17 (Currently Amended): The multi-layer printed wiring board according to claim 12, wherein the core substrate is so constructed that [[a]] the thick conductive layer is disposed as the inner layer and a thin conductive layer is formed as the surface layer disposed on ~~the~~ a surface side.